



# WHITE ELECTRONIC DESIGNS

## W3E64M16S-XSBX Application Note

### W3E64M16S-XSBX PACKAGE CONSTRUCTION + QUALIFICATION

#### ENCAPSULANT

- The encapsulant is not injection molded to control wire sweep effects
- $T_G = 150^\circ\text{C}$
- Moisture sensitivity is to JEDEC level 3

#### INTERPOSER MATERIAL

- $\text{CTE} = 12\text{-}13 \text{ ppm} / ^\circ\text{C}$
- Water absorption = 0.13%

#### BALLS

- Eutectic solder Sn63/Pb37
- Diameter = 0.40mm (0.021) Typical

#### TEST

- Burn-In – 100%-48 hours at  $125^\circ\text{C}$
- Final Electrical Test – 100% at maximum and minimum ambient temperatures

#### Temperature Ranges Available:

$-55^\circ\text{C}$  to  $+125^\circ\text{C}$

$-40^\circ\text{C}$  to  $+85^\circ\text{C}$

$0^\circ\text{C}$  to  $+70^\circ\text{C}$

#### SHIPPING

- Final bake out
- Shipped in JEDEC standard trays and anti-static shielded dry pack bags
- Humidity indicator cards are included
- Desiccant used in dry packs

### QUALIFICATION INFORMATION

Qual for 60 PBGA Product					
Qual Test	# of Pieces	Duration	Reference Standards	Temp. Range	Results
Preconditioning	All Test Samples		EIA/JESD22 Method A113		Pass
Bias Life Test	15	1000 hrs.	EIA/JESD22 Method A108	$125^\circ\text{C}$	15 Pass
Temperature Cycle	15	1000 cycles	EIA/JESD22 Method A104 Condition B	$-55^\circ\text{C}$ to $+125^\circ\text{C}$	15 Pass
85/85 Bias	15	1000 hrs.	EIA/JESD22 Method 101	$85^\circ\text{C}$	15 Pass

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